Filename: PMP5748RevC - BoM.xls
Date: 10/25/2011

PMP5748RevC - Bill of Material

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
3	C1, C2, C3	4.7uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	Std	Std
1	C11	1uF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
1	C12	100pF	Capacitor, Ceramic, 50V, C0G, 5%	603	Std	Std
1	C13	220nF	Capacitor, Ceramic, 16V, X7R, 10%	603	Std	Std
1	C14	3.3nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C15	180pF	Capacitor, Ceramic, 50V, COG, 10%	603	Std	Std
1	C16	100pF	Capacitor, Ceramic, 50V, C0G, 5%	603	Std	Std
1	C17	10nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C4, C5	100nF	Capacitor, Ceramic, 100V, X7R, 10%	805	Std	Std
1	C6	33uF	Capacitor, Aluminum, 100V, 20%	0.406 x 0.457 inch	EEEFK2A330P	Panasonic
1	C7	100nF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
1	C8	4.7uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	Std	Std
2	C9, C10	2x4.7uF	Capacitor, Ceramic, 50V, X7R, 10%	1210	Std	Std
1	D1	3KASMC24A	Diode, Voltage Suppressor, 24V	SMC	3KASMC24A	Vishay
1	D2	BZX84C5V1	Diode, Zener, 5.1V, 225mW	SOT-23	BZX84C5V1	OnSemi
1	D3	10WT10FN	Diode, Schottky, 10A, 100V	DPAK	10WT10FN	Vishay
1	D4	BZX84C39	Diode, Zener, 39V, 225mW	SOT-23	BZX84C39	Vishay
1	D5	BAV99	Diode, Dual Ultra Fast, Series, 200-mA, 70-V	SOT23	BAV99	Fairchild
1	J1	43045-0609	Header, 2X3 3.0 mm, RA	12.65 x 15.40 mm	43045-0609	Molex
1	L1	1uH	Inductor, SMT, 9.0A sat, 6.8A rms, 9mOhm	0.51x0.37 inch	DO3316P-102ML	Coilcraft
1	L2	15uH	Inductor, Dual Winding, 2.51A rms, 4.83A sat, 99mOhm	0.492 x 0.492 inch	DRQ127-220-R	Coiltronics
1	Q1	Si7489DP	MOSFET, PChan, -100V, -28A, 41mOhm	PWRPAK S0-8	Si7489DP	Vishay
1	Q2	Si7850DP	MOSFET, NChannel, 60V, 10.3 A, 22mOhm, 27nC	PWRPAK S0-8	Si7850DP	Vishay
1	Q3	2N7002	MOSFET, N-ch, 60V, 115mA, 1.2-Ohms	SOT23	2N7002	Diodes
1	R1	10.0k	Resistor, Metal Film, 1/4 watt, 1%	1206	Std	Vishay
2	R11, R12	49.9k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R2	0	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R3	402k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R4	10	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R5	1.00k	Resistor, Chip, 1/16W, 1%	603	Std	Std
3	R6, R9, R10	10.0k	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	R7	0.027	Resistor, Chip,1/2W, 1%	1210	Std	Std
1	R8	49.9	Resistor, Chip, 1/16W, 1%	603	Std	Std
1	SHUNT	0.356	Resistor, Chip,1/2W, 1%	1210	Std	Std
5	TP1, TP2, TP3, TP4, TP8	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
2	TP5, TP7	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	U1	TPS40211-Q1	IC, 4.5V-52V I/P, Current Mode Boost Controller	DGQ10	TPS40211-Q1	Texas Instruments

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